



# 1M x 36 Pipelined NoBL™ SRAM Module

## Features

- Operates at 133 MHz
- Uses 512K x 18 high-performance Pipelined NoBL™ synchronous SRAMs
- 2.5V data inputs/outputs

## Functional Description

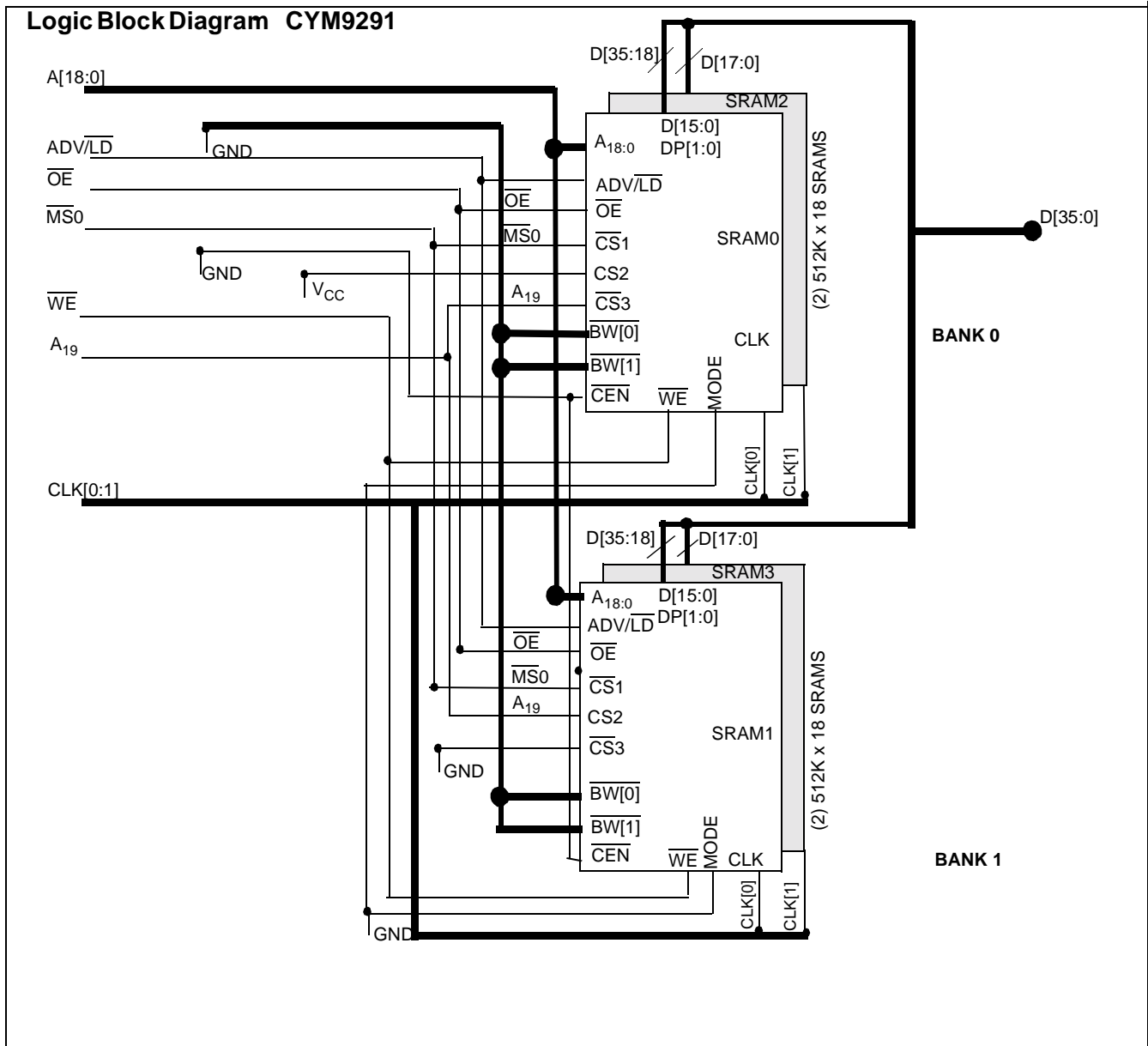
The CYM9291 is a high-performance synchronous pipelined NoBL memory module organized as 1M by 36 bits. These modules are constructed from 512K x 18 NoBL SRAMs in

plastic surface mount packages on an epoxy laminate board with pins. The modules are designed to be incorporated into large memory arrays.

The module is configured as two banks, where each bank has separate chip select controls. Separate clocks are provided for every pair of SRAMs.

Multiple ground pins and on-board decoupling capacitors ensure high performance with maximum noise immunity.

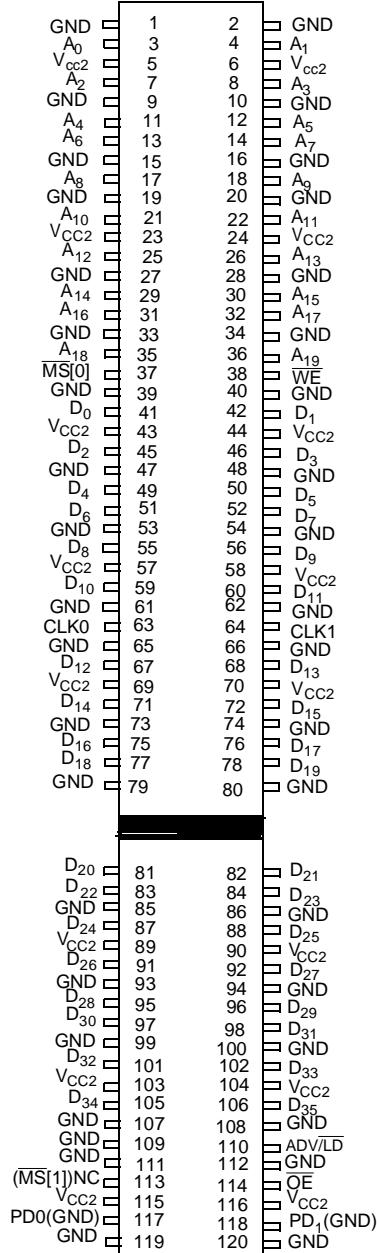
All components on the modules are surface mounted on a multi-layer epoxy laminate (FR-4) substrate.



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**Selection Guide**

| <b>NoBL Pipelined Module</b> |                   |                      |                           |                             |
|------------------------------|-------------------|----------------------|---------------------------|-----------------------------|
| <b>Part Number</b>           | <b>Cache Size</b> | <b>SRAM's Used</b>   | <b>System Clock (MHz)</b> | <b>Data t<sub>CDV</sub></b> |
| CYM9291PZ-133                | 1M x 36           | 4 of 512K x 18(TQFP) | 133                       | 4.4 ns                      |
| CYM9291PZ-117                | 1M x 36           | 4 of 512K x 18(TQFP) | 117                       | 4.8ns                       |

**Pin Configuration**
**Dual Read-Out ZIP  
Top View**


**Pin Definitions**

| Signal                           | Description                        |
|----------------------------------|------------------------------------|
| V <sub>CC2</sub>                 | 2.5V Supply                        |
| GND                              | Ground                             |
| A[19:0]                          | Addresses from processor           |
| $\overline{OE}$                  | Output Enable                      |
| $\overline{WE}$                  | Write Enable                       |
| $\overline{MS}[0]$               | Chip Select for the module         |
| PD <sub>0</sub> –PD <sub>1</sub> | Presence Detect output pins        |
| D[35:0]                          | Data lines from processor          |
| CLK[0:1]                         | Clock lines to the module          |
| ADV/LD                           | Advance Load Signal from processor |
| NC                               | Signal not connected on module     |
| NC(Pin 113)                      | Reserved for Depth expansion       |
| RSVD                             | Reserved                           |

**Presence Detect Pins**

|                     | PD <sub>1</sub> | PD <sub>0</sub> |
|---------------------|-----------------|-----------------|
| CYM9291PZ - 1M x 36 | GND             | GND             |

**Maximum Ratings**

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... -55°C to +125°C

Ambient Temperature with Power Applied..... 0°C to +70°C

Supply Voltage to Ground Potential ..... -0.3V to +3.6V

DC Voltage Applied to Outputs in High Z State ..... -0.3V to +3.6V

DC Input Voltage ..... -0.5V to +3.6V

Output Current into Outputs (LOW) ..... 20 mA

**Operating Range**

| Range      | Ambient Temperature | V <sub>CC</sub> |
|------------|---------------------|-----------------|
| Commercial | 0°C to +70°C        | 2.5V ± 5%       |

**Electrical Characteristics Over the Operating Range**

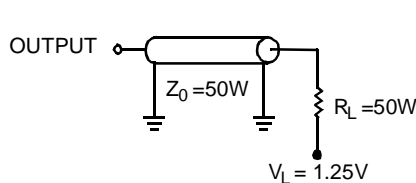
| Parameter              | Description                              | Test Condition  | Min. | Max.                  | Unit |
|------------------------|--|---|------|-----------------------|------|
| V <sub>IH</sub>        | Input HIGH Voltage                       |   | 1.7  | V <sub>CC</sub> + 0.3 | V    |
| V <sub>IL</sub>        | Input LOW Voltage                        |   | -0.3 | 0.7                   | V    |
| V <sub>OH</sub>        | Output HIGH Voltage                      | V <sub>CC</sub> = Min. I <sub>OH</sub> = -1 mA  | 2.0  |                       | V    |
| V <sub>OL</sub>        | Output LOW Voltage                       | V <sub>CC</sub> = Min. I <sub>OL</sub> = 1 mA   |      | 0.2                   | V    |
| I <sub>CC</sub> (9291) | V <sub>CC</sub> Operating Supply Current | V <sub>CC</sub> = Max., I <sub>OUT</sub> =0 mA, f=f <sub>MAX</sub> =1/t <sub>RC</sub> |      | 1680                  | mA   |

**Capacitance<sup>[1]</sup>**

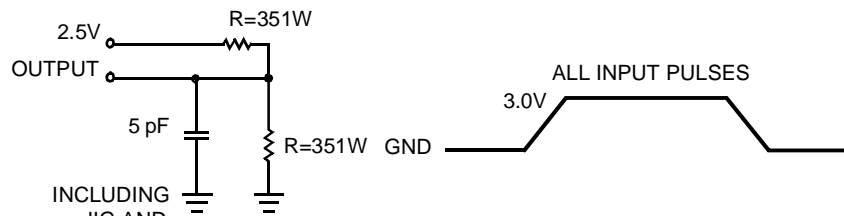
| Parameter        | Description               | Test Conditions   | Max. | Unit |
|------------------|---------------------------|---|------|------|
| C <sub>A</sub>   | Address Input Capacitance | T <sub>A</sub> = 25°C, f = 1 MHz, V <sub>CC</sub> = 2.5 V | 24   | pF   |
| C <sub>I</sub>   | Control Input Capacitance | T <sub>A</sub> = 25°C, f = 1 MHz, V <sub>CC</sub> = 2.5 V | 24   | pF   |
| C <sub>O</sub>   | Input/Output Capacitance  | T <sub>A</sub> = 25°C, f = 1 MHz, V <sub>CC</sub> = 2.5 V | 16   | pF   |
| C <sub>CLK</sub> | Clock Capacitance         | T <sub>A</sub> = 25°C, f = 1 MHz, V <sub>CC</sub> = 2.5 V | 6    | pF   |

**Note:**

1. Tested initially and after any design or process changes that may affect these parameters.

**AC Test Loads and Waveforms**


(a)



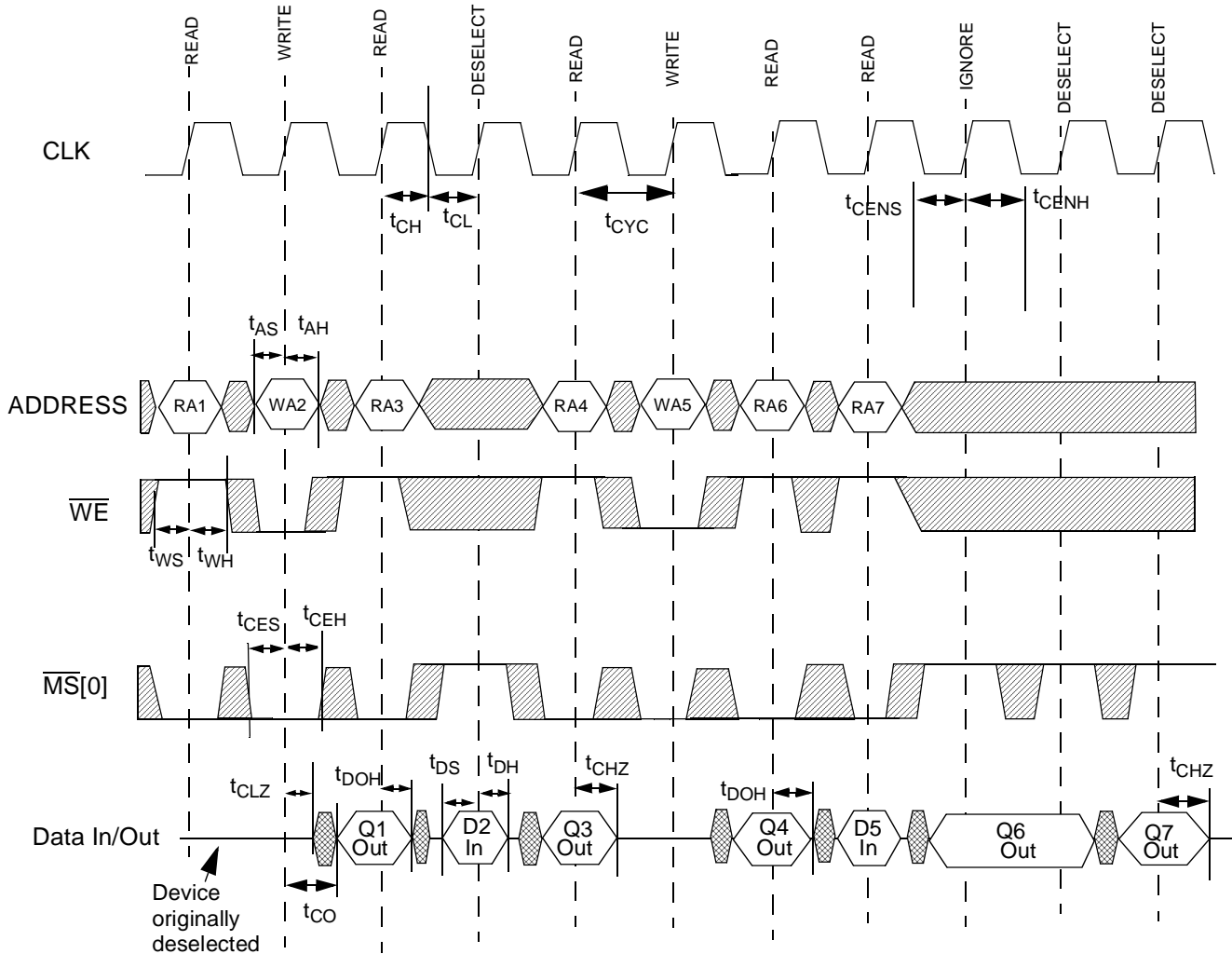
(b)

**Switching Characteristics** Over the Operating Range<sup>[2]</sup>

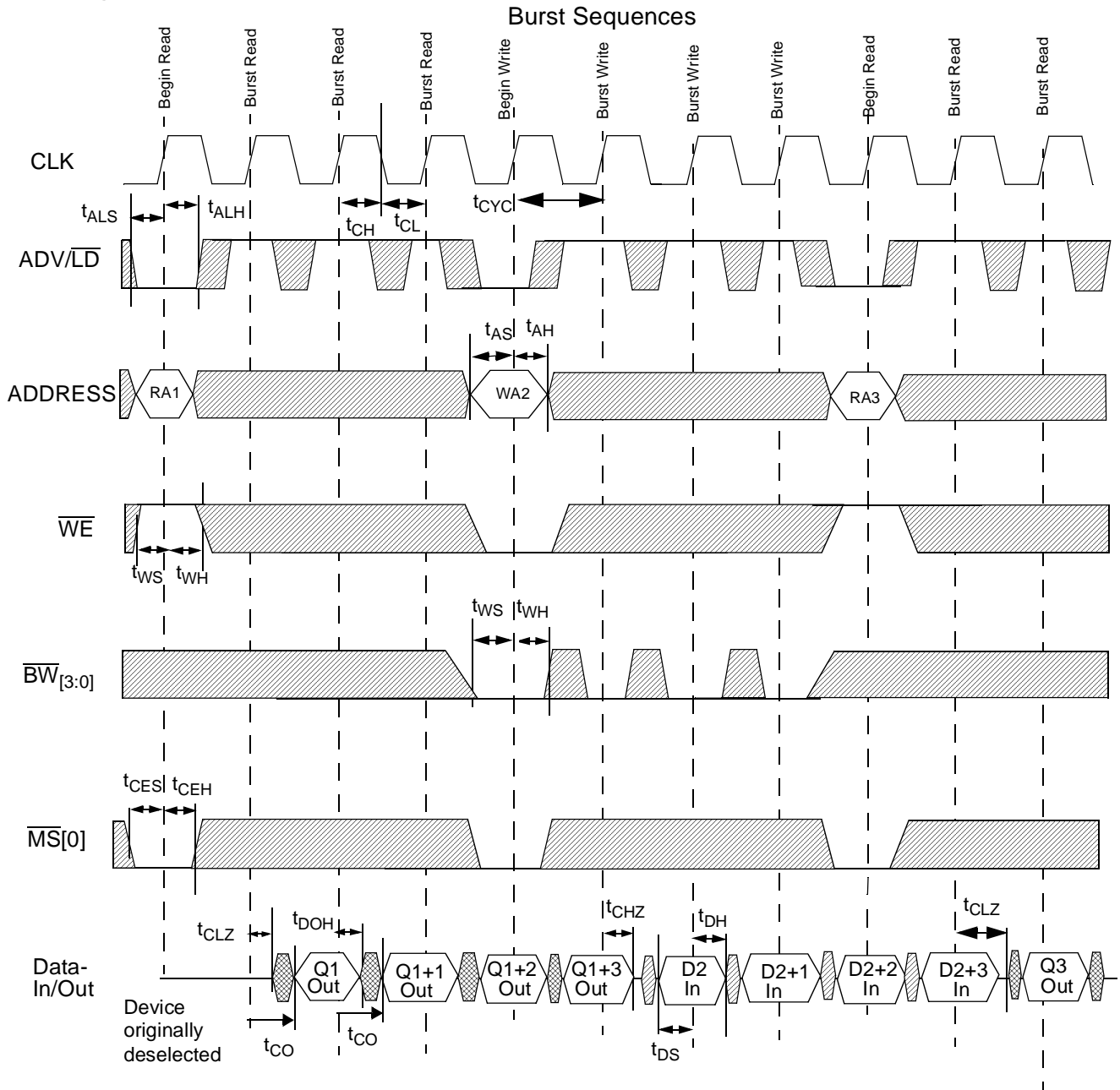
| Parameter           | Description  | 133  |      | 117  |      | Unit |
|---------------------|--|------|------|------|------|------|
|                     |  | Min. | Max. | Min. | Max. |      |
| <b>Clock</b>        |  |      |      |      |      |      |
| $t_{CYC}$           | Clock Cycle Time   | 7.5  |      | 8.6  |      | ns   |
| $F_{MAX}$           | Maximum Operating Frequency                                |      | 133  |      | 117  | MHz  |
| $t_{CH}$            | Clock HIGH   | 2.5  |      | 3    |      | ns   |
| $t_{CL}$            | Clock LOW  | 2.5  |      | 3    |      | ns   |
| <b>Output Times</b> |  |      |      |      |      |      |
| $t_{CDV}$           | Data Output Valid After CLK Rise                           |      | 4.4  |      | 4.8  | ns   |
| $t_{EOV}$           | $\overline{OE}$ LOW to Output Valid <sup>[3, 5]</sup>      |      | 4.4  |      | 4.8  | ns   |
| $t_{DOH}$           | Data Output Hold After CLK Rise                            | 2.3  |      | 2.3  |      | ns   |
| $t_{CHZ}$           | Clock to High-Z <sup>[3, 4, 5]</sup>                       |      | 3.8  |      | 3.8  | ns   |
| $t_{CLZ}$           | Clock to Low-Z <sup>[3, 4, 5]</sup>                        | 2.3  |      | 2.3  |      | ns   |
| $t_{EOHZ}$          | $\overline{OE}$ HIGH to Output High-Z <sup>[3, 4, 5]</sup> |      | 3.8  |      | 3.8  | ns   |
| $t_{EOLZ}$          | $\overline{OE}$ LOW to Output Low-Z <sup>[3, 4, 5]</sup>   | 0    |      | 0    |      | ns   |
| <b>Set-up Times</b> |  |      |      |      |      |      |
| $t_{AS}$            | Address Set-Up Before CLK Rise                             | 1.5  |      | 1.5  |      | ns   |
| $t_{DS}$            | Data Input Set-Up Before CLK Rise                          | 1.5  |      | 1.5  |      | ns   |
| $t_{WES}$           | $\overline{WE}$ Set-Up Before CLK Rise                     | 1.5  |      | 1.5  |      | ns   |
| $t_{ALS}$           | $ADV/\overline{LD}$ Set-Up Before CLK Rise                 | 1.5  |      | 1.5  |      | ns   |
| $t_{CES}$           | Chip Selects Set-Up  | 1.5  |      | 1.5  |      | ns   |
| <b>Hold Times</b>   |  |      |      |      |      |      |
| $t_{AH}$            | Address Hold After CLK Rise                                | 0.5  |      | 0.5  |      | ns   |
| $t_{DH}$            | Data Input Hold After CLK Rise                             | 0.5  |      | 0.5  |      | ns   |
| $t_{WEH}$           | $\overline{WE}$ Hold After CLK Rise                        | 0.5  |      | 0.5  |      | ns   |
| $t_{ALH}$           | $ADV/\overline{LD}$ Hold after CLK Rise                    | 0.5  |      | 0.5  |      | ns   |
| $t_{CEH}$           | Chip Selects Hold After CLK Rise                           | 0.5  |      | 0.5  |      | ns   |

**Notes:**

- A/C test conditions assume signal transition time of 2 ns or less, timing reference levels, input pulse levels and output loading shown in AC Test Load for 2.5V devices.
- $t_{CHZ}$ ,  $t_{CLZ}$ ,  $t_{EOV}$ ,  $t_{EOLZ}$ , and  $t_{EOHZ}$  are specified with AC test conditions shown in part (a) of AC Test Loads. Transition is measured  $\pm 200$  mV from steady-state voltage.
- At any given voltage and temperature,  $t_{EOHZ}$  is less than  $t_{EOLZ}$  and  $t_{CHZ}$  is less than  $t_{CLZ}$  to eliminate bus contention between SRAMs when sharing the same data bus. These specifications do not imply a bus contention condition, but reflect parameters guaranteed over worst case user conditions. Device is designed to achieve High-Z prior to Low-Z under the same system conditions.
- This parameter is sampled and not 100% tested.

**Switching Waveforms**
**Read/Write/Deselect Timing**
**READ/WRITE/DESELECT Sequence**


All chip enables need to be active in order to select the device. Any chip enable can deselect the device. RAX stands for Read Address X, WAX stands for Write Address X, DX stands for Data-in for location X, Qx stands for Data-out for location X. ADV/LD held LOW.  $\overline{OE}$  held LOW.

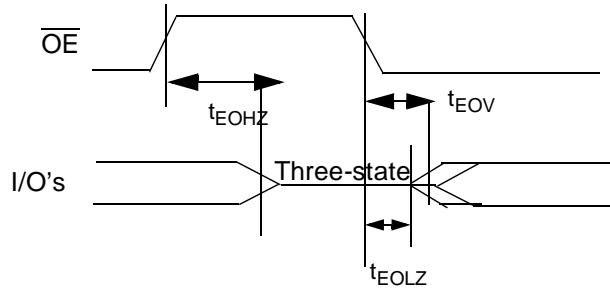
**Switching Waveforms (continued)**
**Burst Timing**


All chip enables need to be active in order to select the device. Any chip enable can deselect the device. RAX stands for Read Address X, WA stands for Write Address X, Dx stands for Data-in for location X, Qx stands for Data-out for location X. CEN held LOW. During burst writes, byte writes can be conducted by asserting the appropriate  $\overline{BW}_{[3:0]}$  input signals. Burst order determined by the state of the Mode input.  $\overline{OE}$  held LOW.

▨ = DON'T CARE    ▩ = UNDEFINED



**Switching Waveforms** (continued)

 $\overline{\text{OE}}$  Timing

**Ordering Information**

| Speed (MHz) | Ordering Code  | Package Name | Package Type | Description            | Operating Range |
|-------------|----------------|--------------|--------------|------------------------|-----------------|
| 133         | CYM9291PZ-133C | PZxx         | 120-Pin ZIP  | Pipelined NoBL 1M x 36 | Commercial      |
| 117         | CYM9291PZ-117C | PZxx         | 120-Pin ZIP  | Pipelined NoBL 1M x 36 |                 |

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**Package Diagrams**
**PZ13: 120 Pin Dual Sided ZIP Module**
